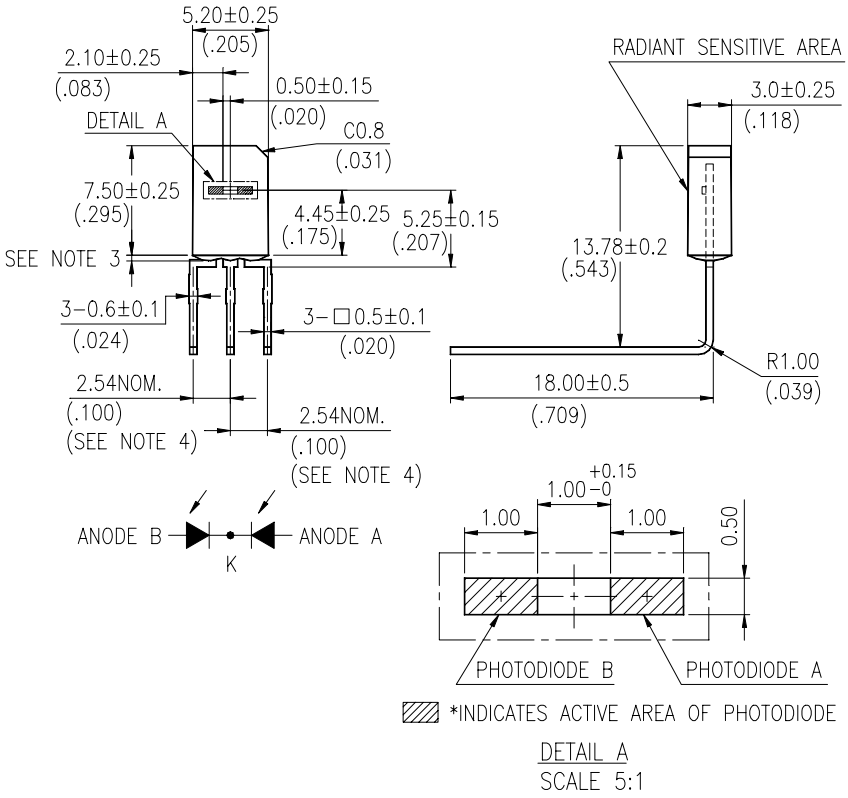
FEATURES

* HIGH PHOTO SENSITIVITY
* SUITABLE FOR INFRARED RADIATION
* LOW JUNCTION CAPACITANCE
* HIGH CUT-OFF FREQUENCY
* FAST SWITCHING TIME

PACKAGE DIMENSIONS



NOTES:
1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25mm(.010") unless otherwise noted.
3. Protruded resin under flange is 1.0mm(.039") max.
4. Lead spacing is measured where the leads emerge from the package.
5. Specifications are subject to change without notice.
6. The epoxy package should filter visible light.

ABSOLUTE MAXIMUM RATINGS AT TA=25℃

PARAMETER	MAXIMUM RATING	UNIT
Power Dissipation	150	mW
Reverse Break Down Voltage	30	V
Operating Temperature Range	-40℃ to + 85℃	
Storage Temperature Range	-55℃ to + 100℃	
Lead Soldering Temperature [1.6mm(.063") From Body]	260℃ for 5 Seconds	

ELECTRICAL OPTICAL CHARACTERISTICS AT TA=25℃

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Reverse Break Down Voltage	$V_{(BR)R}$	30			V	I_R = 100 μA Ee = 0mW/cm²
Reverse Dark Current Voltage	$I_{D(R)}$			30	nA	V_R = 10V Ee = 0mW/cm²
Open Circuit Voltage	V_{OC}		300		mV	λ = 940nm Ee = 1.0mW/cm²
Rise Time	Tr		50		nsec	V_R = 10V λ = 940nm R_L = 1KΩ
Fall Time	Tf		50		nsec	
Short Circuit Current (*Note 1)	I_S	1.1	1.5		μA	V_R = 5V λ = 940nm Ee = 0.1mW/cm²
Total Capacitance	C_T		10		pF	V_R = 3V f = 1MHZ Ee = 0mW/cm²
Wavelength of the Max Sensitivity	λ_{SMAX}		900		nm	

*Note 1: Photodiode A light current is with in 5% of photodiode B light current.

TYPICAL ELECTRICAL / OPTICAL CHARACTERISTICS CURVES

(25℃ Ambient Temperature Unless Otherwise Noted)

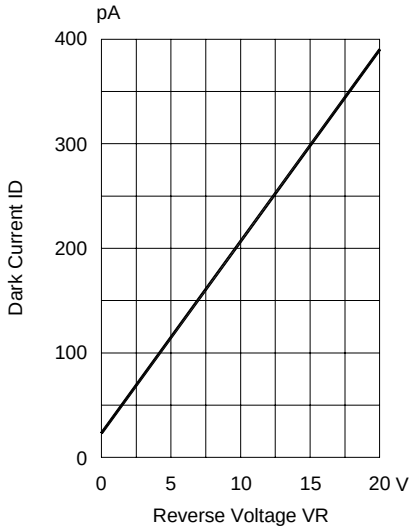


Fig.1 DARK CURRENT VS. REVERSE VOLTAGE
TA=25° C, Ee=0 mW/cm²

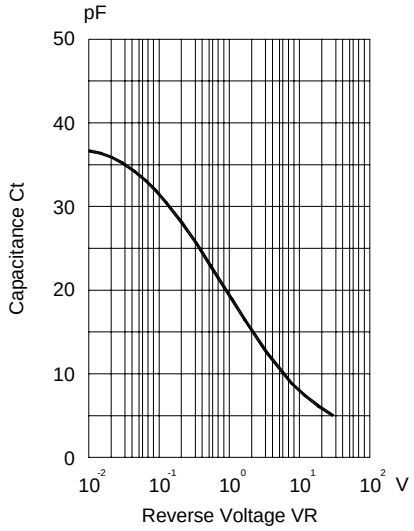


Fig.2 CAPACITANCE VS. REVERSE VOLTAGE
F=1MHZ; Ee=0mW/cm²

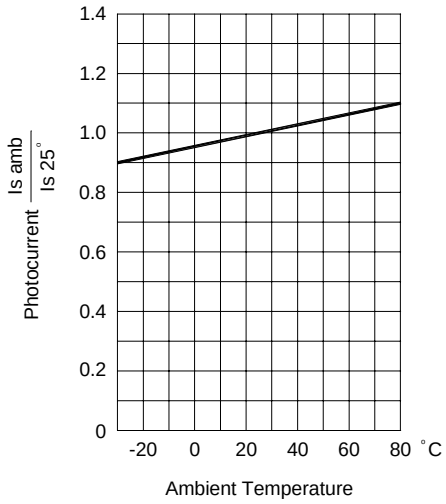


Fig.3 PHOTOCURRENT VS. AMBIENT TEMPERATURE

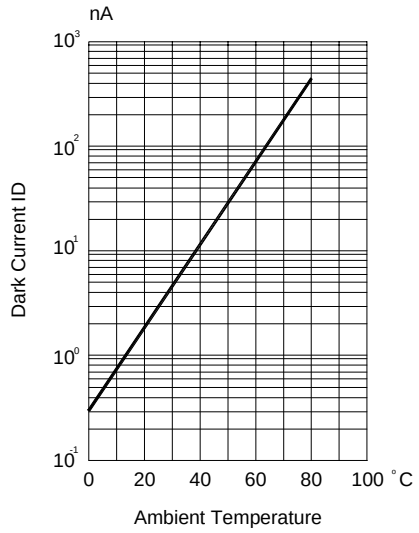


Fig.4 DARK CURRENT AMBIENT TEMPERATURE
VR=10V, Ee=0mW/cm²

TYPICAL ELECTRICAL / OPTICAL CHARACTERISTICS CURVES

(25℃ Ambient Temperature Unless Otherwise Noted)

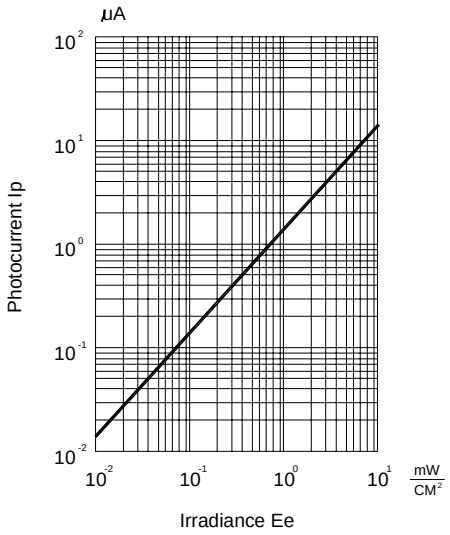


Fig.5 PHOTOCURRENT VS IRRADIANCE λ= 940 nm

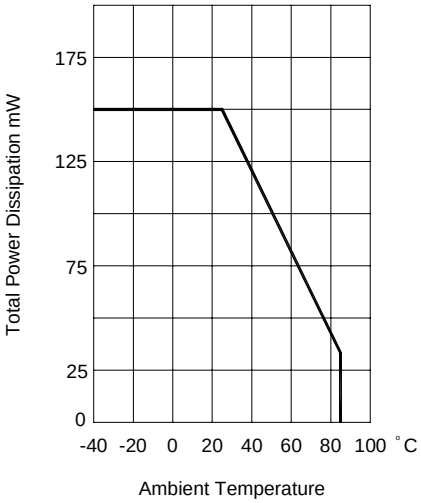


Fig.6 TOTAL POWER DISSIPATION VS AMBIENT TEMPERATURE

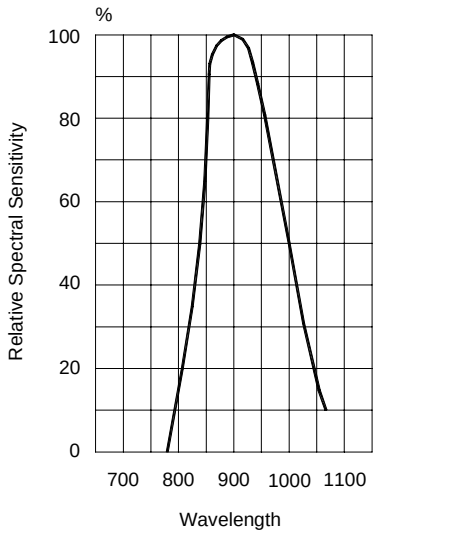


Fig.7 RELATIVE SPECTRAL SENSITIVITY VS WAVELENGTH